

MECHANICAL CASE OUTLINE

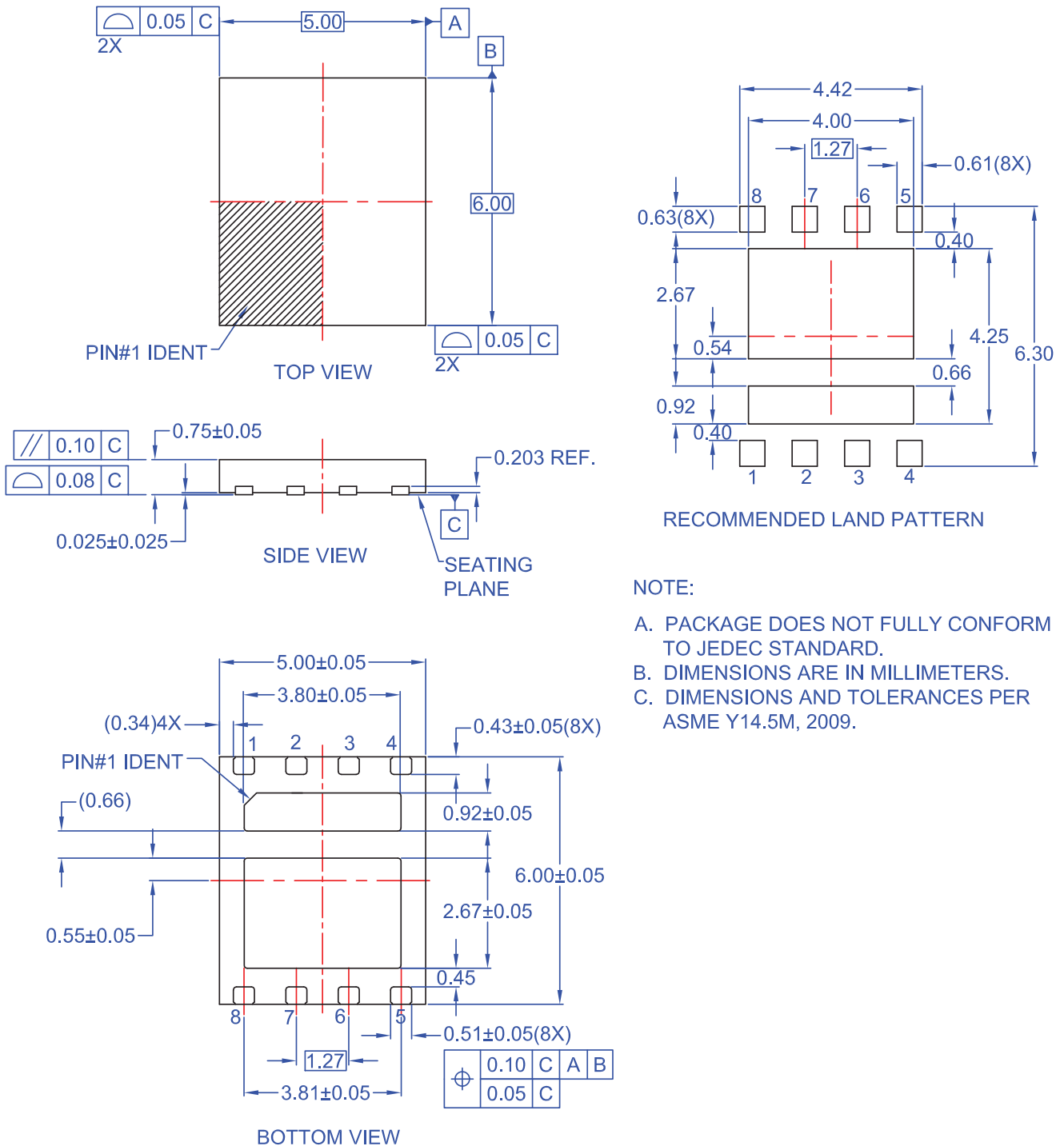
PACKAGE DIMENSIONS

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WDFN8 5x6, 1.27P
CASE 506DS
ISSUE O

DATE 31 AUG 2016



NOTE:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

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